



ZMM55-C2V4 ~ SERIES

500mW SURFACE MOUNT ZENER DIODE

FEATURES

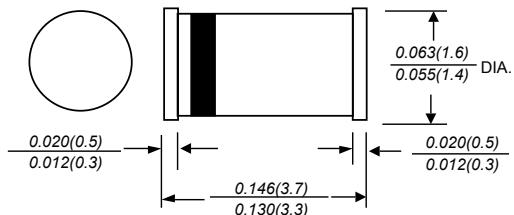
- Planar Die construction
- 500mW Power Dissipation
- Ideally Suited for Automated Assembly Processes
- Both normal and Pb free product are available :
 - Normal : 80~95% Sn, 5~20% Pb
 - Pb free: 98.5% Sn above

MECHANICAL DATA

- Case: Molded Glass MINI-MELF
- Terminals: Solderable per MIL-STD-750, Method 2026
- Polarity: See Diagram Below
- Approx. Weight: 0.03 grams
- Mounting Position: Any



MINI-MELF / LL-34



Dimensions in inches and (millimeters)

ABSOLUTE MAXIMUM RATINGS(LIMITING VALUES)(TA=25°C)

	Symbols	Value	Units
Zener current see table "Characteristics"			
Power dissipation at TA=25°C	P _{tot}	500 ¹⁾	mW
Junction temperature	T _J	175	°C
Storage temperature range	T _{STG}	-55 to + 175	°C

1)Valid provided that at a distance of 8mm from case are kept at ambient temperature

ELECTRICAL CHARACTERISTICS(TA=25°C)

	Symbols	Min.	Typ.	Max.	Units
Thermal resistance junction to ambient	R _{THA}			0.31)	K/mW
Forward voltage at I _F =100mA	V _F			1.1	V
1)Valid provided that leads at a distance of 8mm from case are kept at ambient temperature					

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RATINGS AND CHARACTERISTIC CURVES

FIG.1- BREAKDOWN CHARACTERISTICS

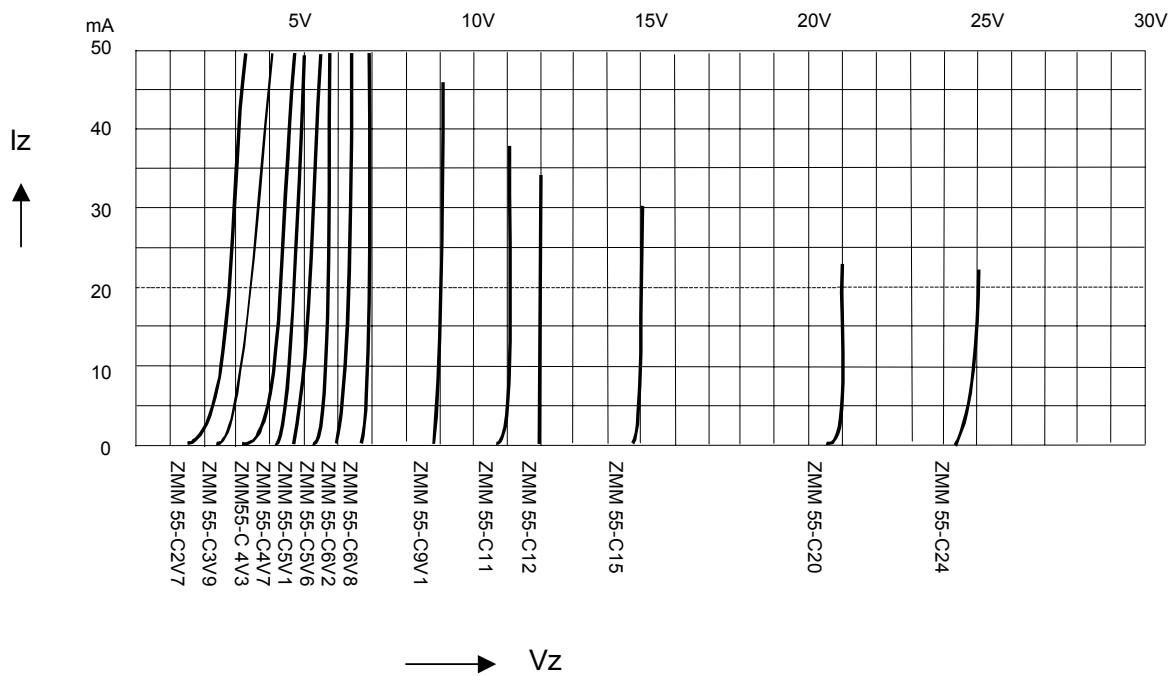


FIG.2- POWER , TEMPERATURE DERATING CURVE

